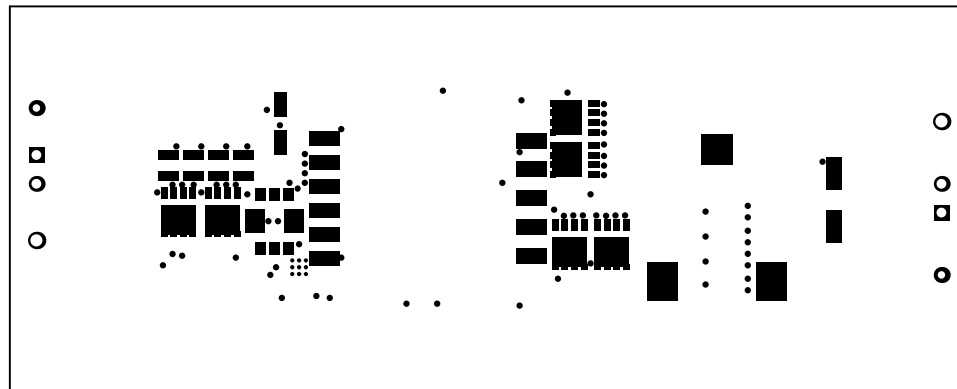
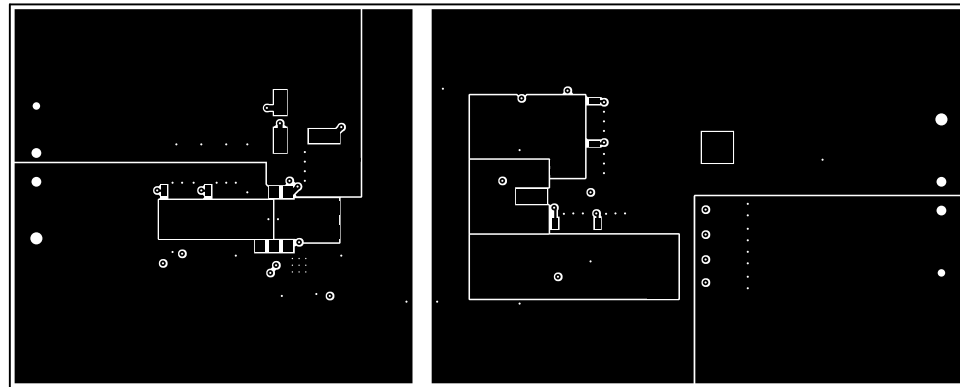


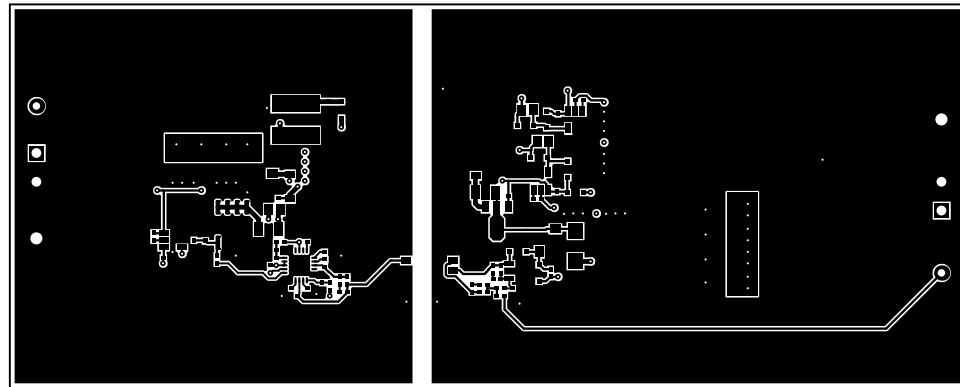
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/25/2014 11:46:10 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/25/2014 11:46:11 AM	TEXAS INSTRUMENTS	



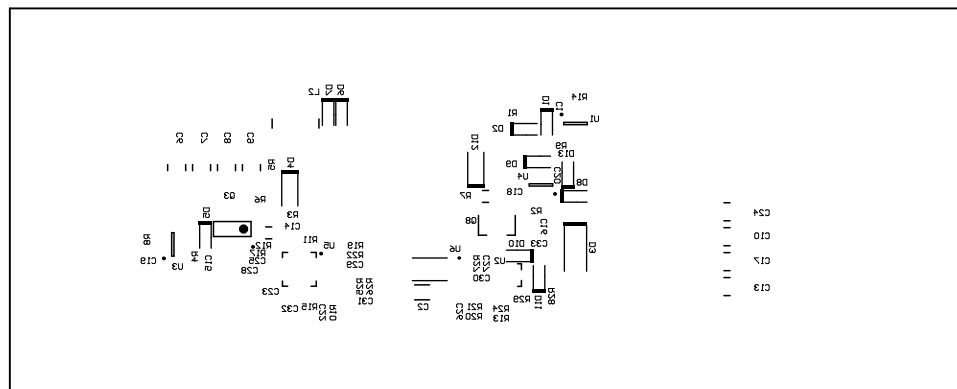
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/25/2014 11:46:12 AM	TEXAS INSTRUMENTS	



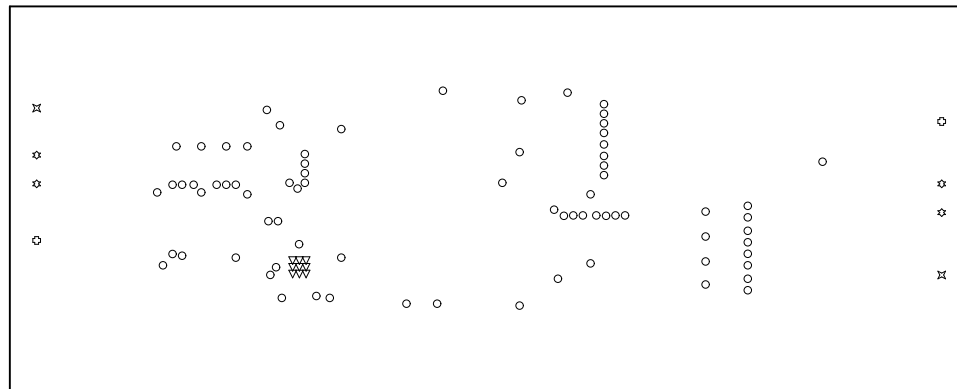
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/25/2014 11:46:12 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/25/2014 11:46:13 AM	TEXAS INSTRUMENTS	



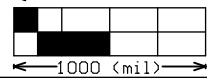
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/25/2014 11:46:14 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	9	7.874mil (0.2mm)	PTH	Round
○	75	12mil (0.305mm)	PTH	Round
x	2	40mil (1.016mm)	PTH	Round
*	4	51.181mil (1.3mm)	PTH	Round
⊕	2	63mil (1.6mm)	PTH	Round
	92 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/25/2014 11:46:14 AM	TEXAS INSTRUMENTS	



1000 (mil)

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10395	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/25/2014 11:46:15 AM	TEXAS INSTRUMENTS	

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